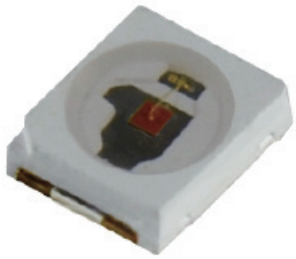
2T03X5RX00031SA1

Ultra high reliability and luminous efficacy ,PLCC LED Series are optimized to be used as lighting for automotive signal lighting designs or signboard.



Automotive Lighting | Signal Lighting

Applications :

- Automotive Interior/Exterior Lighting
- Traffic Lighting
- Signal Lighting

Features :

- Package: Ag Plated 2 pad design package with silicone resin
- Dimension: 3.5 mmx2.8 mm
- Chip technology: AlGaInP
- View Angle: 120°
- Color: λ_{dom}=614 nm(Red)
- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)
- MSL: Level 2
- Qualifications: The product qualification test based on the guidelines of AEC-Q102

EDISON
Lighting Design Manufacturing Service

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Lighting Design Manufacturing Service

General Information

Ordering Code Format

2	T	03	X5	RX	00	03	1	S	A	1
X1	X2	X3-X4	X5-X6	X7-X8	X9-X10	X11-X12	X13	X14	X15	X16

X1		X2		X3-X4		X5-X6		X7-X8	
Type		Component		Series		Wattage		Color/CCT	
2	Emitter	T	PLCC	03	3528	X5	0.5W	RX	Red

X9-X10		X11-X12		X13		X14		X15	
CRI(Ra)		Voltage		Leadframe Mode		Leadframe Plating		Model	
00	-	03	3V	1	PCT 0.80H 2PIN	S	Silver	A	Automotive

X16	
Serial Number	
-	-

Lighting Design Manufacturing Service

Absolute Maximum Ratings

Absolute maximum ratings

Parameter		Symbol	Values
Operating Temperature	min. max.	T_{op}	-40 °C 110 °C
Storage Temperature	min. max.	T_{stg}	-40 °C 110 °C
Junction Temperature	max.	T_j	125 °C
Forward current T_J = 25 °C	min. max.	I_F	5 mA 200 mA
Surge Current t ≤ 10 µs; D = 0.005 ; T_J = 25 °C	max.	I_{FS}	300 mA
Reverse voltage T_J = 25 °C	max.	V_R	10 V
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 2)		V_{ESD}	2 kV

Notes: Proper current derating must be observed to maintain junction temperature below the maximum at all time.

Characteristics

I_F = 140 mA; T_J = 25 °C

Parameter		Symbol	Values
Peak Wavelength	typ.	λ_{Peak}	621 nm
Dominant Wavelength	min. typ. max.	λ_{dom}	612 nm 614 nm 620 nm
Viewing angle	typ.	φ	120 °
Forward Voltage	min. typ. max.	V_F	2.05 V 2.15 V 2.35 V
Reverse current V_R= 10 V	typ. max.	I_R	0.01 µA 10 µA
Real thermal resistance junction/solder point	typ. max.	$R_{thJS\ real}$	40 K / W 49 K / W
Electrical thermal resistance junction/ solder point with efficiency ηe = 32 %	typ. max.	$R_{thJS\ elec.}$	27 K / W 33 K / W

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Luminous Intensity Characteristic

Luminous Intensity Characteristics, I_F=140mA , T_J=25˚C

Symbol	Group	Min. Luminous Intensity(mcd)	Max. Luminous Intensity(mcd)	Typ. Luminous Flux(lm)
Iv	DB	5600	7100	19.8
	EA	7100	9000	25.1
	EB	9000	11200	31.5

Note:
The luminous intensity performance is guaranteed within published operating conditions. Edison Opto maintains a tolerance of ±10% on intensity measurements.

Voltage Bin Structure

Voltage Bin Structure, I_F=140mA , T_J=25˚C

Symbol	Group	Min. Voltage (V)	Max. Voltage (V)
V_F	B05	2.05	2.20
	B20	2.20	2.35
	B35	2.35	2.50

Note:
Forward voltage measurement allowance is ± 0.1V.

Wavelength Bin Structure

Wavelength Bin Structure, I_F=140mA , T_J=25˚C

Symbol	Group	Min. Wd (nm)	Max. Wd (nm)
λ_{dom}	R12	612	616
	R16	616	620

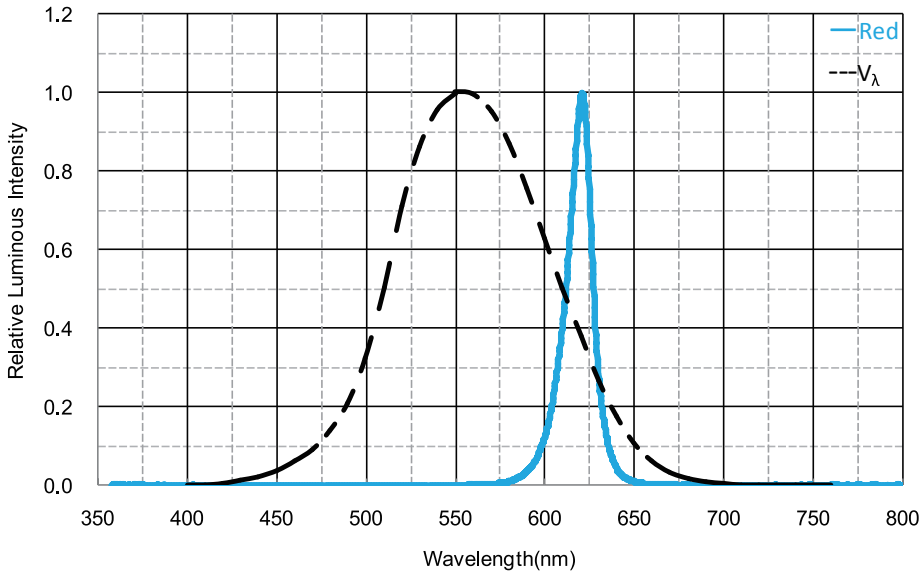
Note:
Dominant wavelength meansurement allowance is ± 1nm.

Lighting Design Manufacturing Service

Characteristic Curves

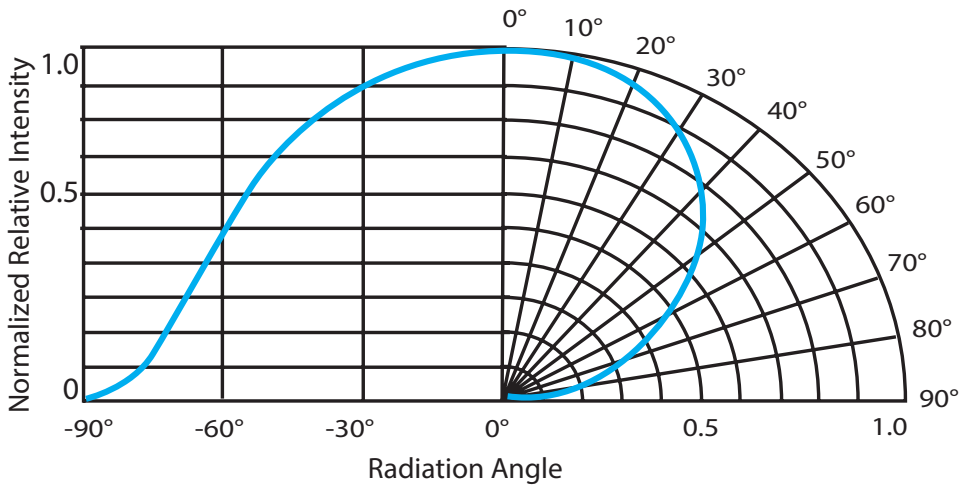
Color Spectrum

I_F =140 mA ; T_J = 25 °C



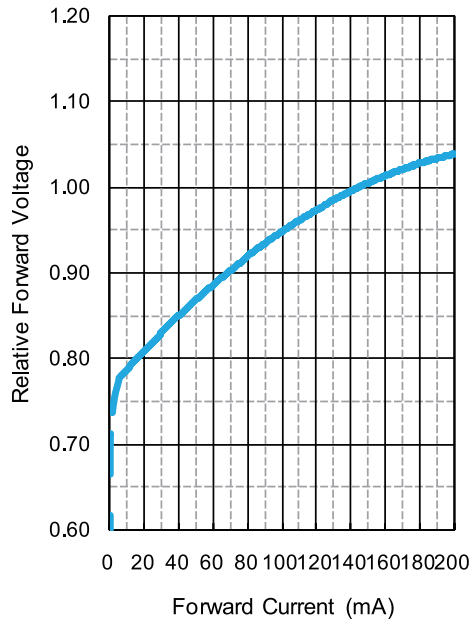
Beam Pattern

I_F =140 mA ; T_J = 25 °C



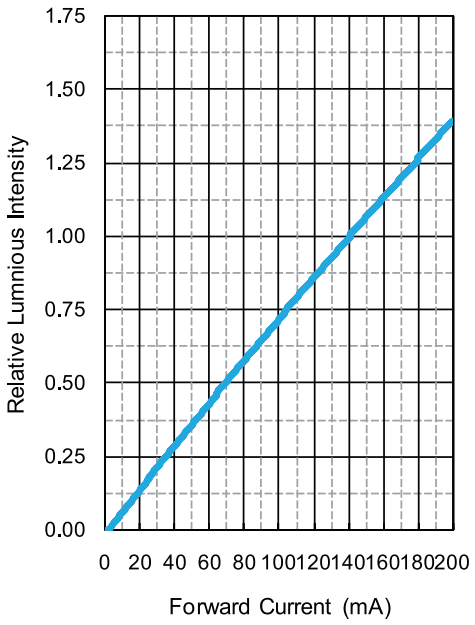
Relative Foward Voltage

$V_F/V_F(140\ mA) = f(V_F); T_J = 25\ °C$



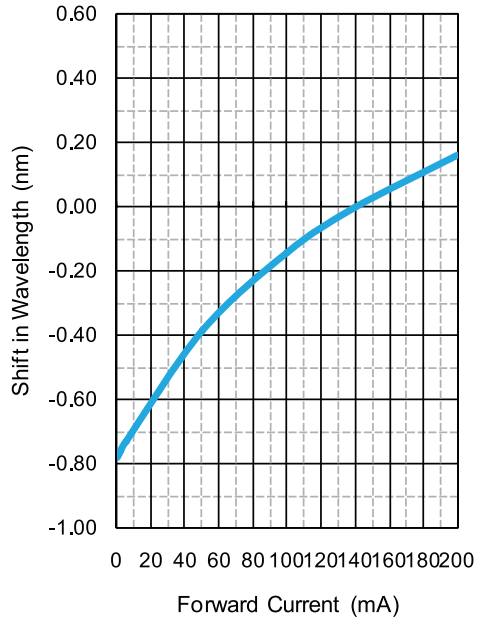
Relative Luminous Intensity

$I_v/I_v(140\ mA) = f(I_v); T_J = 25\ °C$



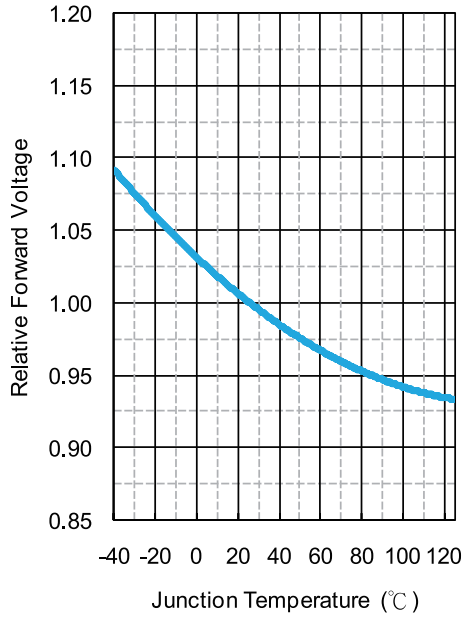
Shift in Dominant Wavelength

$\Delta\lambda_{dom} = \lambda_{dom} - \lambda_{dom}\ (140\ mA); T_J = 25\ °C$



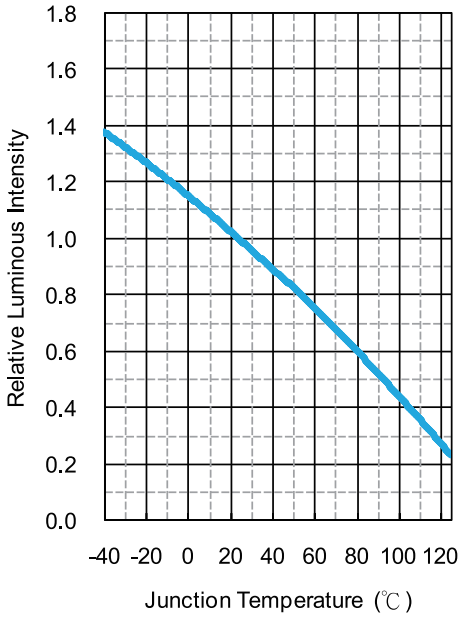
Relative Forward Voltage

$V_F/V_F(25\,°C) = f(V_F);\ I_F = 140$ mA



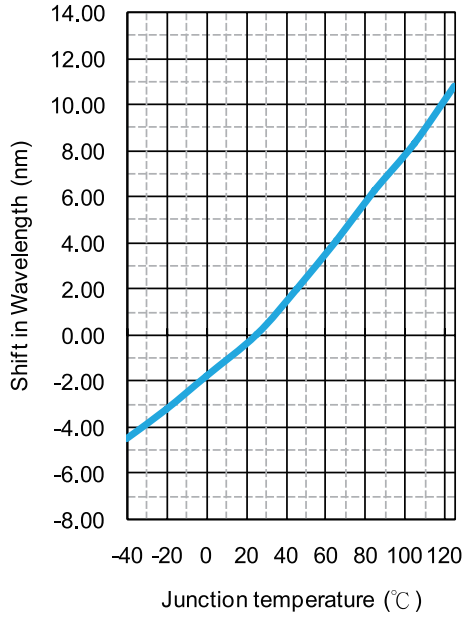
Relative Luminous Intensity

$I_v/I_v(25\,°C) = f(I_v);\ I_F = 140$ mA



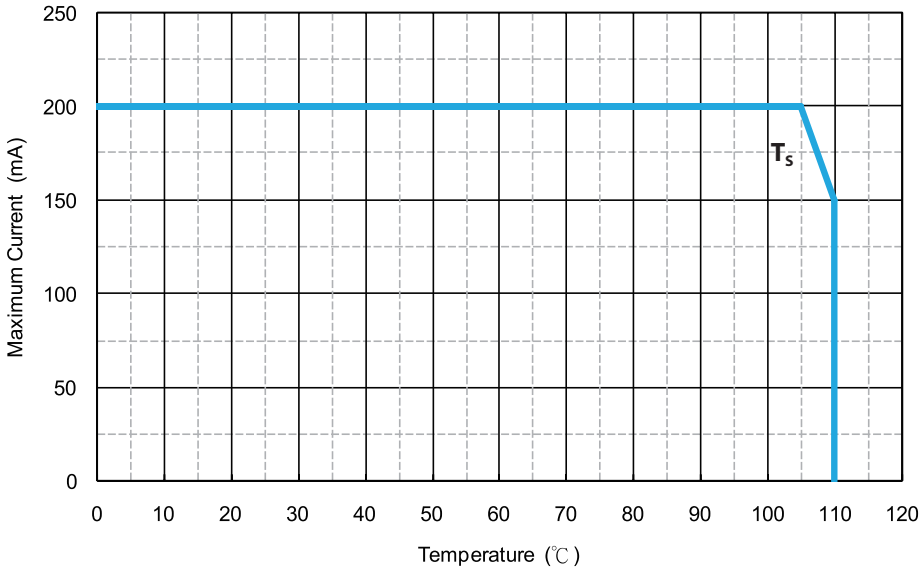
Shift in Dominant Wavelength

$\Delta\lambda_{dom} = \lambda_{dom} - \lambda_{dom}\,(25\,°C);\ I_F = 140$ mA



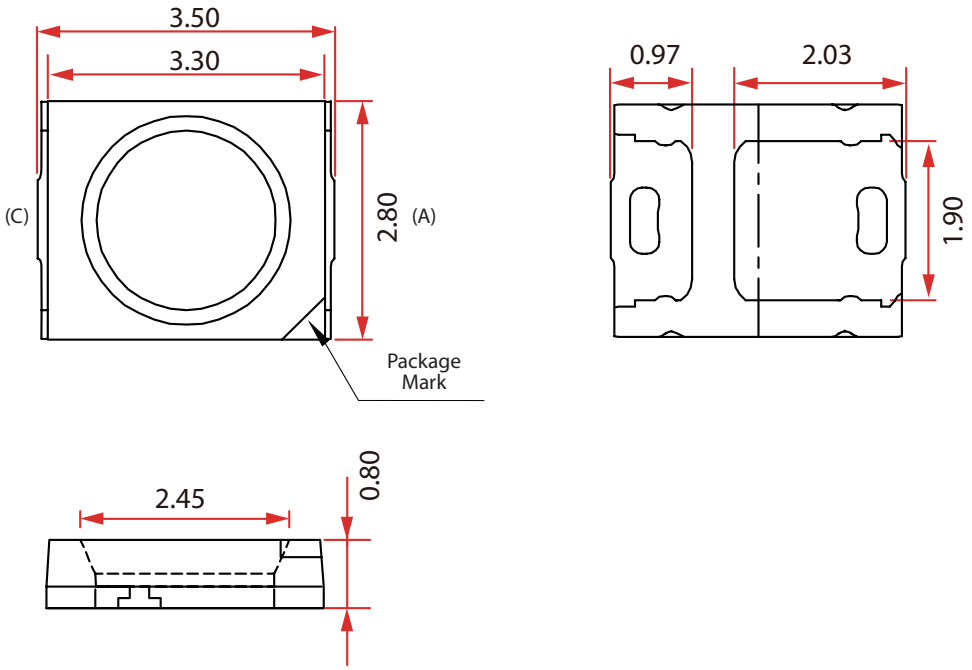
Max. Permissible Forward Current

$I_F = f(T)$

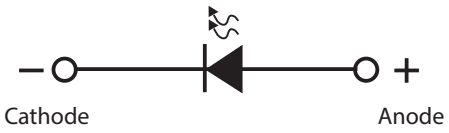


Mechanical Dimensions

Dimensional Drawing

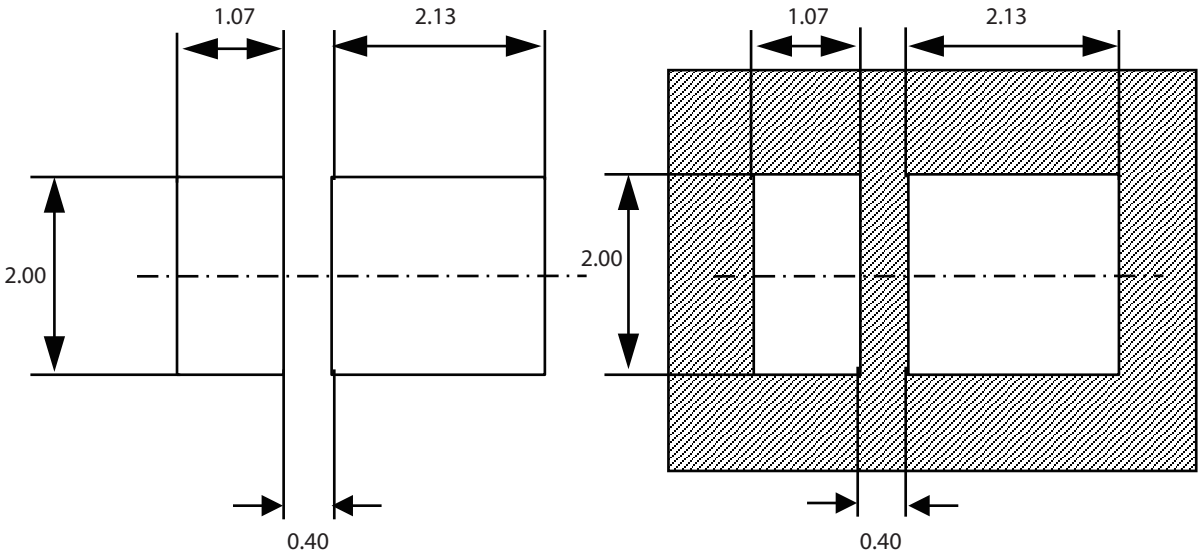


Circuit



Notes:
1. All dimensions are measured in mm.
2. Tolerance : ± 0.1 mm
3. Approximate Weight : 25.0 mg

Recommended Solder Pad



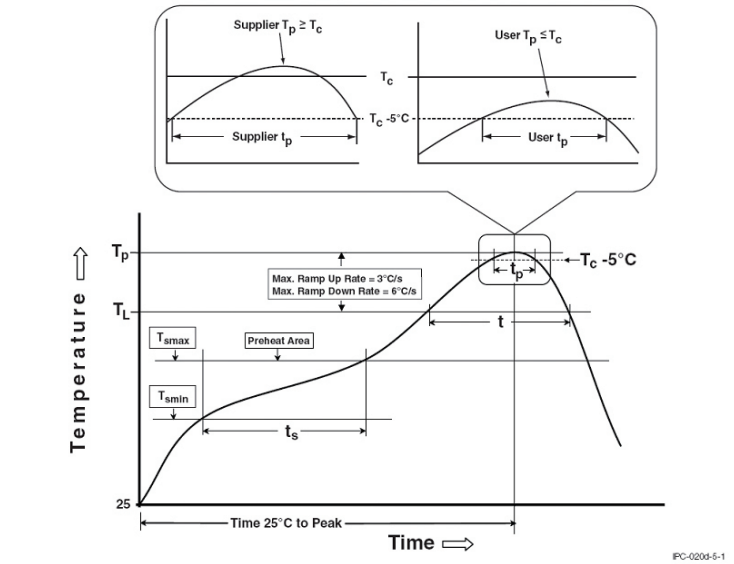
Paddesign for improved heat dissipation Solder resist Cu-area>16mm^2 per pad

Notes:
1. All dimensions are measured in mm.
2. Tolerance : ± 0.1 mm

Lighting Design Manufacturing Service

Reflow Profile

The following reflow profile is from IPC/JEDEC J-STD-020D which provided here for reference.

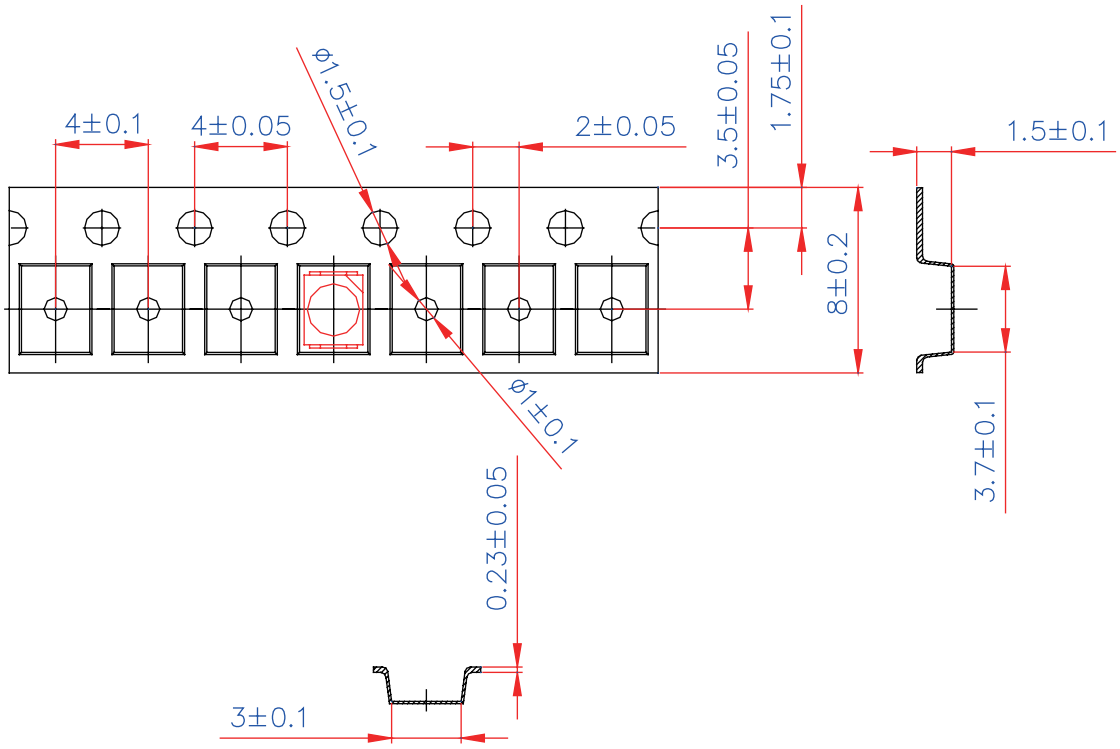


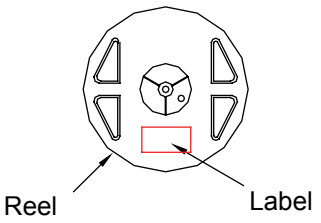
Reflow Profiles

Classification Reflow Profiles

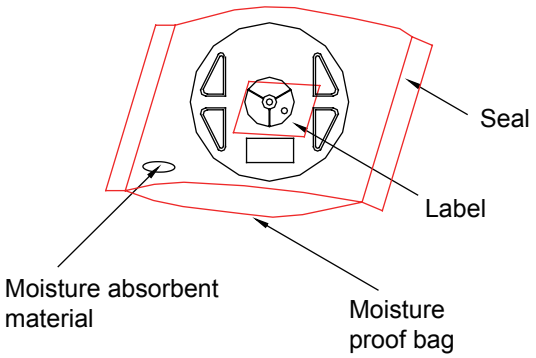
Profile Feature	Pb-Free Assembly
Preheat & Soak Temperature min (Tsmin) Temperature max (Tsmax) Time (Tsmin to Tsmax) (ts)	150 °C 200 °C 60-120 seconds
Average ramp-up rate (Tsmax to Tp)	3 °C/second max.
Liquidous temperature (TL) Time at liquidous (tL)	217 °C 60-150 seconds
Peak package body temperature (Tp)	255 °C ~260 °C
Classification temperature (Tc)	260 °C
Time (tp) within 5 °C of the specified classification temperature (Tc)	30 seconds
Average ramp-down rate (Tp to Tsmax)	6°C/second max.
Time 25°C to peak temperature	8 minutes max.

Product Packaging Information





Taping reel dimensions



Package & label

Item	Quantity	Total	Dimensions(mm)
Reel	4,000pcs	4,000pcs	R=178
Starting with 250pcs empty,and 150pcs empty at the last			

Cautions

(1) Moisture monitoring is vital during the storage of LEDs for if too much moisture is absorbed, interface delamination and optical performance degradation will occur. Therefore, products should be packed in moisture-proof aluminum bags so as to reduce moisture absorption to the lowest degree during transportation and storage. Included moisture-proof aluminum bag are the key indicators that they will change from brown to azure if bags are invaded by moisture.

(2) Soldering process in compliance with the range of the conditions stated above should be conducted after opening the moisture-proof aluminum bag. The rest LEDs should be stored in a hermetically sealed container, silica gel desiccants included. And the original moisture-proof aluminum bags are recommended.

(3) If the "Period After Opening" storage time is too long or silica gel desiccants don't maintain blue any more, baking process should be done once.

Lighting Design Manufacturing Service

Revision History

Versions	Description	Release Date
1	Establish a Datasheet	2020/05/28

About Edison Opto

Edison Opto is a leading manufacturer of high power LED and a solution provider experienced in LDMS. LDMS is an integrated program derived from the four essential technologies in LED lighting applications- Thermal Management, Electrical Scheme, Mechanical Refinement, Optical Optimization, to provide customer with various LED components and modules. More Information about the company and our products can be found at www.edison-opto.com

www.edison-opto.com

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LED.Detective@edison-opto.com.tw